

**Applications**

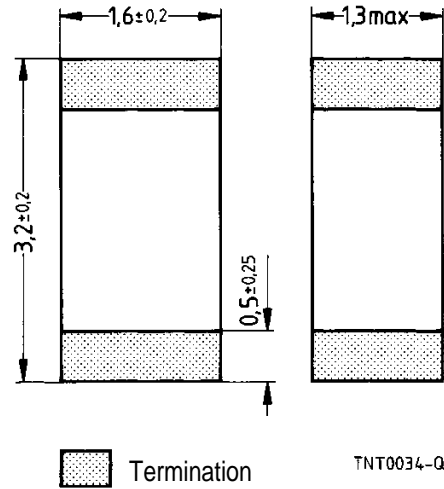
- Temperature compensation
- Hybrid circuits
- Data systems
- Telecom systems
- Automotive electronics
- LC displays

**Features**

- Small dimensions, EIA size 1206
- Silver palladium terminations
- Cost-effective
- Suitable for automatic placement
- Suitable for wave and reflow soldering
- Available on tape (PU: 4000 pcs)

**Options**

Alternative resistance ratings and resistance tolerance < 5% available on request



Dimensions in mm  
Approx. weight 18 mg

Climatic category (IEC 68-1)		55/125/21	
Max. power at 25 °C (on PCB)	$P_{25}$	300	mW
Resistance tolerance	$\Delta R/R_N$	$\pm 5\%, \pm 10\%, \pm 20\%$	
Rated temperature	$T_N$	25	°C
B value tolerance	$\Delta B/B$	$\pm 3\%$	
Dissipation factor (on PCB)	$\delta_{th}^{1)}$	approx. 5	mW/K
Thermal cooling time constant (on PCB)	$\tau_c^{1)}$	approx. 10	s
Heat capacity	$C_{th}^{1)}$	approx. 50	mJ/K

Type	$R_{25}$ Ω	No. of R/T characteristic	$B_{25/100}$ K	Ordering code
C 621/2,2 k/+	2,2 k	1308	3060	B57621-C222-+62
C 621/3,3 k/+	3,3 k	1309	3520	B57621-C332-+62
C 621/4,7 k/+	4,7 k	1309	3520	B57621-C472-+62
C 621/10 k/+	10 k	1010	3530	B57621-C103-+62
C 621/15 k/+	15 k	1008	3560	B57621-C153-+62
C 621/22 k/+	22 k	1008	3560	B57621-C223-+62
C 621/33 k/+	33 k	2003	3980	B57621-C333-+62
C 621/47 k/+	47 k	2001	3920	B57621-C473-+62
C 621/68 k/+	68 k	2001	3920	B57621-C683-+62

+: J for  $\Delta R/R_N = \pm 5\%$   
 K for  $\Delta R/R_N = \pm 10\%$   
 M for  $\Delta R/R_N = \pm 20\%$

1) Depends on mounting situation

Type	$R_{25}$ $\Omega$	No. of R/T characteristic	$B_{25/100}$ K	Ordering code
C 621/100 k/+	100 k	<a href="#">4901</a>	3950	B57621-C104-+62
C 621/150 k/+	150 k	<a href="#">2903</a>	4200	B57621-C154-+162
C 621/220 k/+	220 k	<a href="#">2903</a>	4200	B57621-C224-+62
C 621/330 k/+	330 k	<a href="#">1014</a>	4250	B57621-C334-+62
C 621/470 k/+	470 k	<a href="#">1014</a>	4250	B57621-C474-+62

+: J for  $\Delta R/R_N = \pm 5\%$   
 K for  $\Delta R/R_N = \pm 10\%$   
 M for  $\Delta R/R_N = \pm 20\%$

**Reliability data**

Tested on standardized PCB in accordance with IEC 60068-2-21

Test	Standard	Test conditions	$\Delta R_{25}/R_{25}$ (typical)	Remarks
Storage in dry heat	IEC 60068-2-2	Storage at upper category temperature $T: 125\text{ }^\circ\text{C}$ $t: 1000\text{ h}$	< 3 %	
Storage in damp heat, steady state	IEC 60068-2-3	Temperature of air: $40\text{ }^\circ\text{C}$ Relative humidity of air: 93 % Duration: 21 days	< 3 %	No visible damage
Rapid temperature cycling	IEC 60068-2-14	Lower test temperature: $-55\text{ }^\circ\text{C}$ Upper test temperature: $125\text{ }^\circ\text{C}$ Number of cycles: 10	< 3 %	
Endurance		$P_{\max}$ : 300 mW Duration: 1000 h	< 5 %	
Solderability	IEC 60068-2-58	Solderability: $215\text{ }^\circ\text{C}/4\text{ s}$ $235\text{ }^\circ\text{C}/2\text{ s}$ Resistance to soldering heat: $260\text{ }^\circ\text{C}/10\text{ s}$	< 3 %	95 % of terminations wetted
Robustness of terminations		Bending of carrier (2 mm bending)  Refer also to <a href="#">page 120</a>	< 3 %	No visible damage